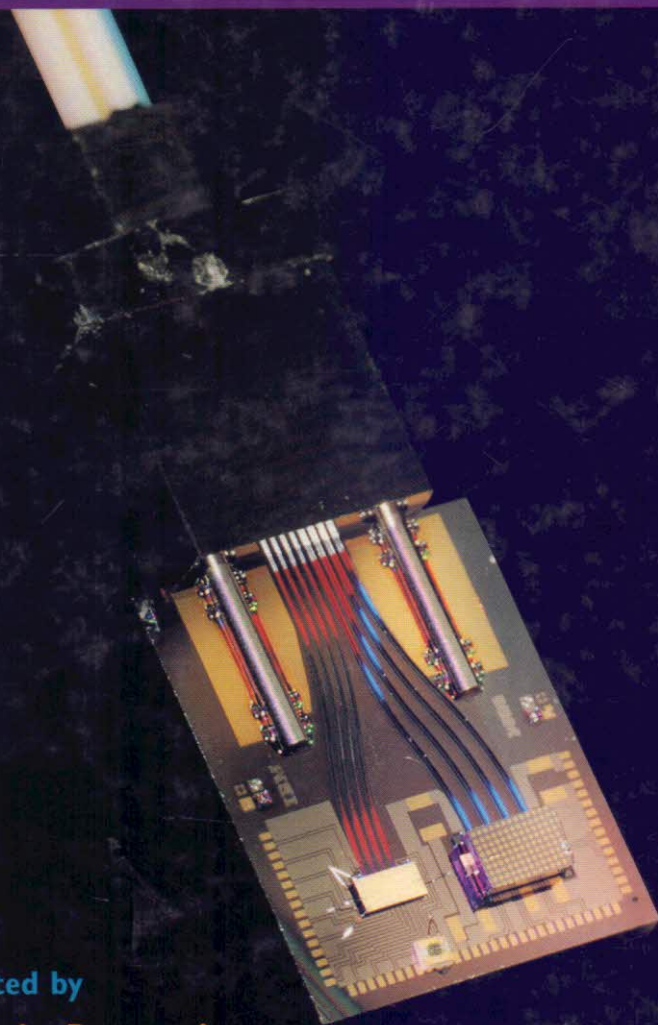




Integrated Optoelectronics



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QUANTUM ELECTRONICS

Principles and Applications

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